



# FAN1950 — 1.5A Low-Voltage, Low-Dropout Regulator

#### **Features**

- 1.5A Minimum Guaranteed Output Current
- 500mV Maximum Dropout at 1.5A
  - Ideal for 2.5V to 1.8V or 1.65V Conversion
  - Ideal for 3.0V to 2.5V Conversion
- Current Limiting and Thermal Shutdown
- Fast Transient Response
- Low Ground Current

### **Applications**

- General-purpose Conversion for Low-voltage CPUs, DSPs, and FPGAs
- SMPS Post Regulators
- Cable / Satellite Set-top Boxes
- PCI Graphics Adapter Cards

# **Description**

The FAN1950 is a 1.5A low-dropout linear regulator that provides a low-voltage, high-current output with a minimum of external components. This device uses a PNP output pass element, achieving a maximum 500mV dropout at 1.5A load current. Over-current limit and thermal shutdown features to ensure full protection.

## **Ordering Information**

| Part Number | Output Voltage | Package            | Packing Method |
|-------------|----------------|--------------------|----------------|
| FAN1950D25X | 2.5V           | 3-Lead TO-252 DPAK | Tape and Reel  |

All packages are lead free per JEDEC: J-STD-020B standard.

# **Typical Application**

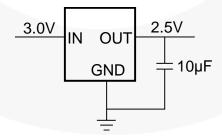


Figure 1. Typical Application

# **Pin Configuration**

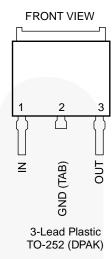


Figure 2. Pin Assignment

# **Pin Definitions**

| Pin# | Name | Description                          |
|------|------|--------------------------------------|
| 1    | IN   | Input Supply Voltage                 |
| 2    | GND  | Ground. This pin and TAB are ground. |
| 3    | OUT  | Output Voltage                       |

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol           | Parameter                              | Min. | Max.               | Unit |
|------------------|--|------|--------------------|------|
| V <sub>IN</sub>  | Supply Voltage                         | -0.2 | 15.0               | V    |
| V <sub>EN</sub>  | Enable Voltage <sup>(1)</sup>          | -0.2 | 15.0               | V    |
| FLAG             | Flag Voltage <sup>(1,2)</sup>          | -0.2 | 15.0               | V    |
| TJ               | Junction Temperature                   | -55  | +150               | °C   |
| T <sub>STG</sub> | Storage Temperature                    | -65  | +150               | °C   |
| TL               | Lead Soldering Temperature, 10 Seconds |      | +300               | °C   |
| P <sub>D</sub>   | Power Dissipation                      |      | Internally Limited | W    |

#### Notes:

- 1. Internally connected through bond wires.
- 2. Flag output cannot be pulled to a voltage higher than V<sub>IN</sub>.

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol        | Parameter                      | Min. | Тур. | Max.  | Unit |
|---------------|--------------------------------|------|------|-------|------|
| Vcc           | Supply Voltage                 | 2.25 |      | 14.00 | V    |
| $\Theta_{JA}$ | Thermal Resistance             |      | 3    |       | °C/W |
| $T_J$         | Junction Operating Temperature | -40  |      | +125  | °C   |

#### **Electrical Characteristics**

 $V_{IN}=V_{OUT}+1V$ ,  $V_{EN}=2.5V$ ,  $T_{J}=+25^{\circ}C$ , unless other wise specified. The • denotes specifications that apply over the full operating temperature range.

| Symbol            | Parameter                        | Conditions   |   | Min.     | Тур. | Max. | Units |
|-------------------|----------------------------------|--|---|----------|------|------|-------|
| V <sub>OUT</sub>  | Output Valtage Talagas           | 10mA ≤ I <sub>OUT</sub> ≤ 1.0A                                     | • | -2       |      | 2    | 0/    |
|                   | Output Voltage Tolerance         | $5mA \leq I_{OUT} \leq 1.0A, \ V_{OUT} + 1V \leq \ V_{IN} \leq 8V$ | • | -2.5 2.5 |      | %    |       |
| R <sub>LINE</sub> | Line Regulation <sup>(3,4)</sup> | $I_{OUT}$ =10mA, $V_{OUT}$ +1 $V \le V_{IN} \le 14V$               |   |          | .06  | .50  | %     |
| R <sub>LOAD</sub> | Load Regulation <sup>(3,4)</sup> | $V_{IN}$ = $V_{OUT}$ + 1 $V$ , 10 $mA \le I_{OUT} \le 1.5A$        |   |          | 0.2  | 1.0  | %     |
| $V_{DO}$          | Drop-out Voltage <sup>(5)</sup>  | I <sub>OUT</sub> =1.5A, ΔV <sub>OUT</sub> =-1%                     | • |          | 350  | 500  | mV    |
| 1                 | Ground Current                   | I <sub>OUT</sub> =750mA  | • |          | 10   | 20   | mΛ    |
| $I_{GND}$         | Ground Current                   | I <sub>OUT</sub> =1.5A   |   |          | 20   | 20   | - mA  |
| I <sub>LOAD</sub> | Minimum Load Current             | $V_{OUT}+1V \le V_{IN} \le 8V$                                     | • |          | 5    | 10   | mA    |
| I <sub>LIM</sub>  | Current Limit                    | V <sub>OUT</sub> =0V, V <sub>IN</sub> =V <sub>OUT</sub> =1V        | • |          | 2.5  |      | Α     |
| $T_{TSD}$         | Thermal Shutdown<br>Temperature  |  |   |          | +150 |      | °C    |
| T <sub>HYS</sub>  | Thermal shutdown<br>Hysteresis   |  |   |          | +10  |      | °C    |
| I <sub>SDO</sub>  | Shutdown Output Current          | $V_{EN} \le 0.8V, \ V_{IN} \le 8V, \ V_{OUT}=0V$                   | • |          |      | 20   | μΑ    |

#### Notes:

- 3. See thermal regulation specifications for changes in output voltage due to heating effects. Load and line regulation are measured at a constant junction temperature by low duty cycle pulse testing.
- 4. Line and load regulation are guaranteed up to the maximum power dissipation. Power dissipation is determined by input/output differential and the output current. Guaranteed maximum output power is not available over the full input/output voltage range.
- 5. Dropout voltage=V<sub>IN</sub>-V<sub>OUT</sub> when V<sub>OUT</sub> decreases to 98% of its nominal output voltage with V<sub>IN</sub>=V<sub>OUT</sub>+1V. For output voltages below 2.25V, dropout voltage is the input-to-output voltage differential with the minimum input voltage being 2.25V. Minimum input operating voltage is 2.25V.

### **Typical Performance Characteristics**

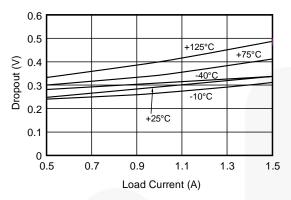


Figure 3. Dropout Voltage vs. Output Current

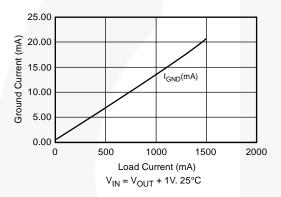


Figure 5. Ground Current vs. Load Current

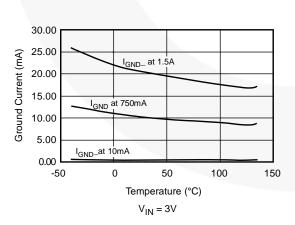


Figure 7. Ground Current vs. Temperature

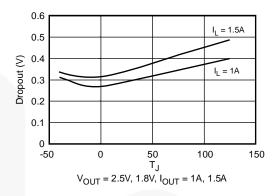


Figure 4. Dropout Voltage vs. Temperature

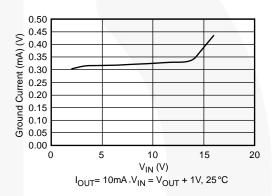


Figure 6. Ground Current vs. Supply Voltage

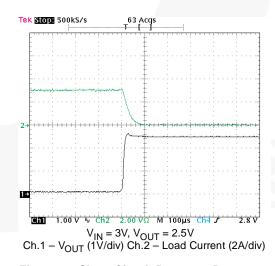


Figure 8. Short-Circuit Recovery Response

# **Typical Performance Characteristics** (Continued)

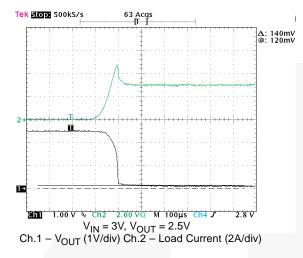
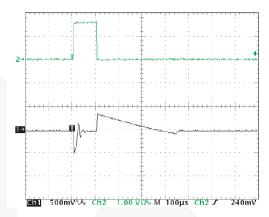


Figure 9. Short-Circuit Transient Response



 $V_{\text{IN}}$ -2.5V,  $V_{\text{OUT}}$ =1.8V,  $C_{\text{IN}}$ =10 $\mu$ F Ceramic  $C_{\text{OUT}}$ =10 $\mu$ F Ceramic Ch1-  $V_{\text{OUT}}$ (AC,0.5V/div) Ch2- Load Current (1A/div)

**Figure 10. Load Transient Response** 

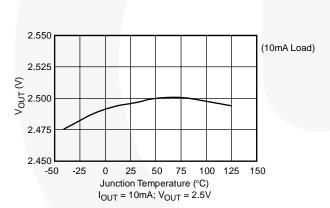
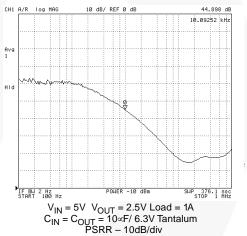


Figure 11. V<sub>OUT</sub> vs. Temperature



PSRR – 10dB/div
Figure 12. Ripple Rejection

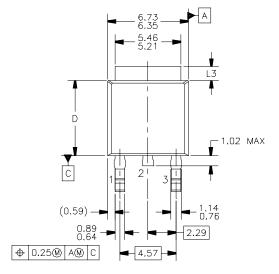
### **Input and Output Capacitor Requirements**

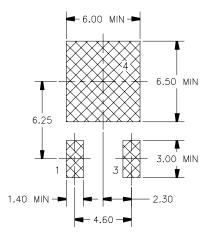
A 4.7µF or greater input capacitor (ceramic or tantalum), installed closely between the  $V_{\text{IN}}$  and GND leads of the part; is required for stability, better transient response, noise, and ripple rejection. A higher value of electrolytic input capacitor can be used if the bulk capacitor of the power supply is located more than 2-4 inches from the device or a large and fast rise-time load is a requirement.

Most LDO regulators require an output capacitor with a recommended value of 10µF. The larger capacitor

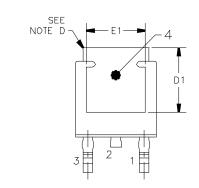
improves the transient response, ripple rejection, and output noise. The low-ESR tantalum capacitors are the best for this application because they provide stable work and good transient response over the temperature range. Using a ceramic capacitor as the output capacitor can provoke instability (oscillation ins the output voltage). Aluminum electrolytic capacitors also can be used if the ESR is below  $3\Omega$ .

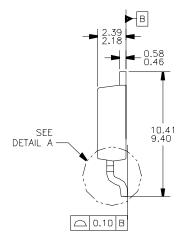
# **Physical Dimensions**

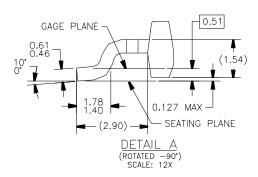




LAND PATTERN RECOMMENDATION







- NOTES: UNLESS OTHERWISE SPECIFIED

  - UNLESS OTHERWISE SPECIFIED
    ALL DIMENSIONS ARE IN MILLIMETERS.
    THIS PACKAGE CONFORMS TO JEDEC, TD-252,
    ISSUE C, VARIATION AA & AB, DATED NOV. 1999.
    DIMENSIONING AND TOLERANCING PER
    ASME Y14.5M-1994. B)

  - HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION,
  - DIMENSIONS L3,D.E1&D1 TABLE

|    | OPTION AA | OPTION AB |
|----|-----------|-----------|
| L3 | 0.89-1.27 | 1.52-2.03 |
| D  | 5.97-6.22 | 5.33-5.59 |
| E1 | 4.32 MIN  | 3.81 MIN  |
| D1 | 5.21 MIN  | 4 57 MIN  |

PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.

Figure 13. 3-Lead TO-252 DPAK Package

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